

COATING METHOD

ABSTRACT

A coating method of coating a face side of a wafer with a solid resin layer includes a holding step of holding, on a holding table, a reverse side of the wafer, the reverse side being opposite the face side of the wafer, an applying step, after the holding step, of applying a liquid resin to the face side of the wafer or a plate-shaped object, a heating step, after the applying step, of heating the liquid resin, and a pressing step, after the heating step, of pressing at least either the plate-shaped object or the wafer to affix the plate-shaped object and the wafer to each other with the liquid resin interposed therebetween. Air bubbles trapped in the liquid resin are ruptured in the heating step.

[FIG. 1]